## 506754272 07/07/2021

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
TAI-YEN PENG	10/20/2017
HUI-HSIEN WEI	10/19/2017
WEI-CHIH WEN	10/20/2017
PIN-REN DAI	10/20/2017
CHIEN-MIN LEE	10/20/2017
HAN-TING TSAI	10/20/2017
JYU-HORNG SHIEH	10/20/2017
CHUNG-TE LIN	10/20/2017

## **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.		
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State/Country:	TAIWAN		
Postal Code:	300-78		

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17369671

#### **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:	R. BURNS ISRAELSEN	
SIGNATURE: /R. Burns Israelsen, Reg. No. 42685/		

PATENT REEL: 056781 FRAME: 0662

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DATE SIGNED: 07/07/2021

Total Attachments: 3
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PATENT REEL: 056781 FRAME: 0663

## ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title)				
MEMORY DEVICE AND FABRICATION METHOD THEREOF				
The PATENT RIGHTS referred to in this agreement are:				
(check one) \( \subseteq a patent application for this invention, executed by the ASSIGNOR(S)				
concurrently with this assignment.				
☑U.S. patent application Serial No. 16/397,871, filed April 29, 2019				
☐a U.S. patent application based on PCT International Application				
Nofiled on (date)(U.S. patent application				
Serial No, if known).				
U.S. patent No, issued				
The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of				
the patents and patent applications identified above.				
The PATENT RIGHTS assigned under this agreement are:				
(check one) ⊠U.S. patent rights only.				
☐Worldwide patent rights. In this case, the assignee shall have the right to				
claim the benefit of the filing date of any U.S. or foreign patent application				
for this invention.				
The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures				
appear on page 2 of this Assignment and any Supplemental Sheet(s).				
The ASSIGNEE referred to in this agreement is:				
(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.				
(Address) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU,				
<u>ΓΑΙΨΑΝ 300, R.O.C.</u>				
The ASSIGNEE is:				
(check one)  ☐An individual.				
A Partnership.				
☐A Corporation ofTAIWAN, R.O.C(specify state or country)				
(other)				
El AGGIGNODOS				
The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and				
aluable consideration, receipt of which is acknowledged, hereby assign(s) the following				

rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

> **PATENT** REEL: 056781 FRAME: 0664

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THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. INVENTION TITLE: MEMORY DEVICE AND FABRICATION METHOD THEREOF

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Tai-Yen PENG Name of sole or first inventor	Tai-Yen Peng Signature	$\frac{\sim 1//20/\sim}{\text{Date}}$
Hui-Hsien WEI  Name of second inventor, if any	Hui - Hsien WEI Signature	<u>2-11/10/19</u> Date
Wei-Chih WEN  Name of third inventor, if any	Wei-Chih WEN Signature	2017 /10/20 Date
Pin-Ren DAI  Name of fourth inventor, if any	Pin-Ren DAI Signature	$\frac{201)/10/20.}{\text{Date}}$
Chien-Min LEE  Name of fifth inventor, if any	Chien-Min Lee Signature	Date
Han-Ting TSAI  Name of sixth inventor, if any	Han-Ting Tsui Signature	>9 17/10/20 Date
Jyu-Horng SHIEH  Name of seventh inventor, if any	Jyu Horny Shiel	2017/10/2N Date

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Chung-Te LIN

Name of eighth inventor, if any

Signature

Date

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**RECORDED: 07/07/2021**